

### STANDALONE WAFER PREALIGNER

## LPA812-3

**Innovative, high-performance, all-in-one design** eliminates external controller and interconnecting cables while maintaining drop-in compatibility

Driven by ultra low inertia brushless motors for **smooth, instant response**

Advanced scanning electronics capable of detecting **transparent, semi-transparent and opaque objects** without mechanical repositioning between different wafer sizes

Motion control software featuring a comprehensive set of commonly used commands enabling **compatibility and interface with a variety of semiconductor platforms**

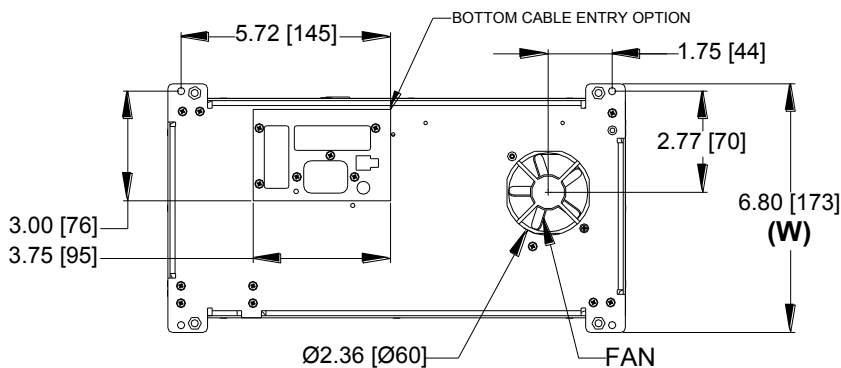
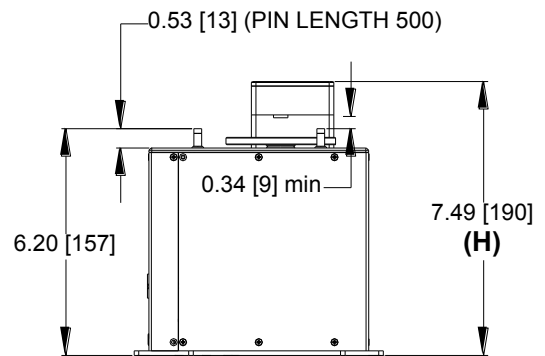
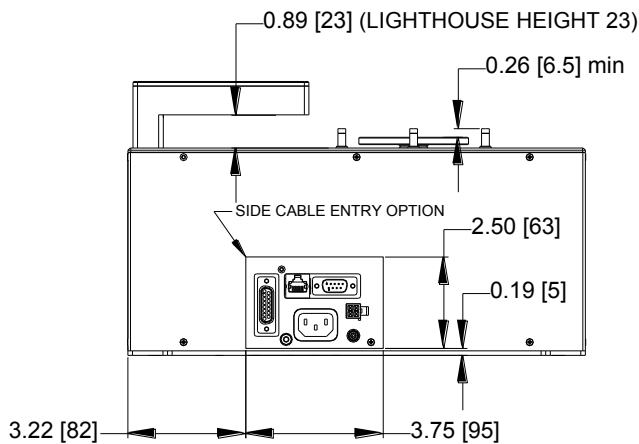
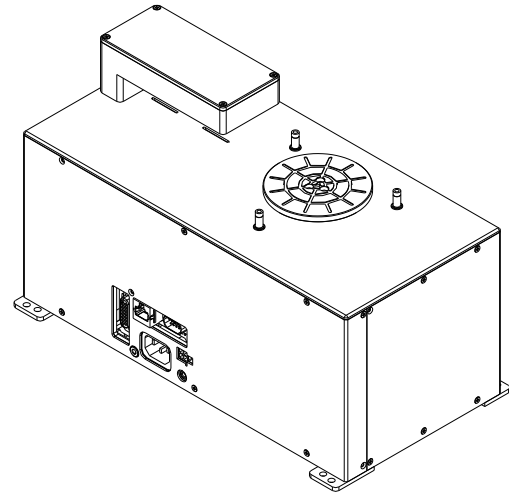
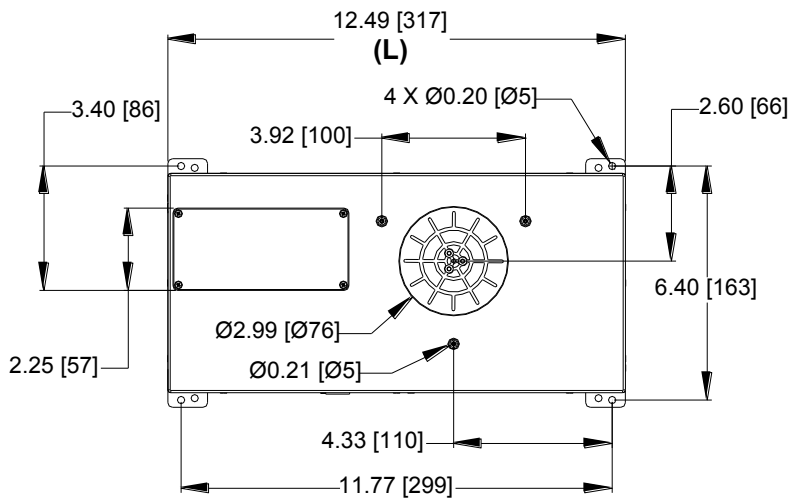
Typical alignment cycle time of less than four seconds facilitates the achievement of **maximum system throughput**



### LPA812-3 SPECIFICATIONS

|                                    |                          |                                                         |
|------------------------------------|--------------------------|---------------------------------------------------------|
| <b>Wafer Diameter</b>              |                          | 200mm, 300mm                                            |
| <b>Wafer Opacity</b>               |                          | Transparent, Semi-Transparent, Opaque                   |
| <b>Square Substrates</b>           |                          | Applicable                                              |
| <b>Wafer Handling</b>              |                          | Vacuum Chuck and Pins                                   |
| <b>Centering Accuracy</b>          |                          | ±25um on the Prealigner Chuck                           |
| <b>Angular Accuracy (3 Sigma)</b>  | <b>10000 CPR Encoder</b> | ±0.04° on the Prealigner Chuck                          |
|                                    | <b>24000 CPR Encoder</b> | ±0.02° on the Prealigner Chuck                          |
| <b>Servo Axes</b>                  |                          | Three                                                   |
| <b>Host Communication</b>          |                          | RS232, Ethernet                                         |
| <b>Max Initial Wafer Offset</b>    |                          | 12mm                                                    |
| <b>Body Dimensions (W x L x H)</b> |                          | 173mm x 317mm x 190mm                                   |
| <b>Footprint Compatibility</b>     |                          | LPA312-3, LPA1218-3<br>LPA8ET-3, LPA12ET-3              |
| <b>Weight</b>                      |                          | 5.40kg                                                  |
| <b>Facilities Required</b>         |                          | 100-240VAC, 50/60Hz, 48VA, or 24VDC/2A<br>Vacuum 12" Hg |
| <b>Flat/Notch Compatibility</b>    |                          | SEMI Standards Compliant                                |
| <b>Cleanliness</b>                 |                          | Class 1                                                 |
| <b>MTBF</b>                        |                          | More than 70000 hours                                   |

## LPA812-3 GENERAL DIMENSIONS



NOTE: All Dimensions — inch [mm]

For model numbers and options download: [LPA Series Prealigners Ordering Guide.pdf](#)